# **Specification of Thermoelectric Module**

**TEC1-06306** 

#### **Description**

The 63 couples, 20 mm × 40 mm size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

#### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

#### **Application**

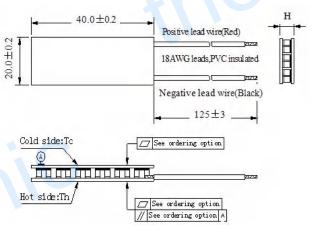
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

#### **Performance Specification Sheet**

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	7.8	8.5	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max(</sub> amps)	5.7	5.7	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	28.6	30.8	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	1.05	1.13	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

#### Geometric Characteristics Dimensions in millimeters

## **Manufacturing Options**



1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

**B. Sealant:** 

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

#### C. Ceramics:

A. Solder:

#### **D. Ceramics Surface Options:**

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

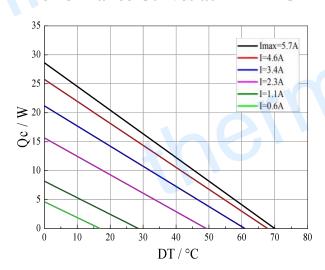
#### **Ordering Option**

Suffix	Thickness	Flatness/ Parallelism (mm)	Lead wire length(mm)			
	H (mm)		Standard/Optional length			
TF	$0:3.7 \pm 0.1$	0: 0.08/0.08	150±3/Specify			
TF	$1:3.7 \pm 0.03$	1: 0.03/0.03	150±3/Specify			
Eg. TF01: Thickness $3.7 \pm 0.15$ (mm) and Flatness $0.08/0.08$ (mm)						

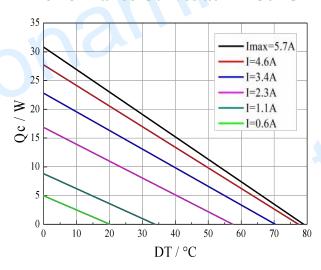
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**TEC1-06306** 

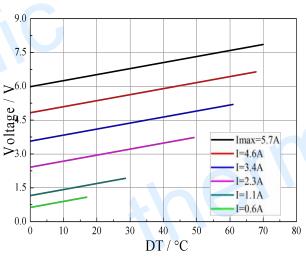
#### Performance Curves at Th=27 °C

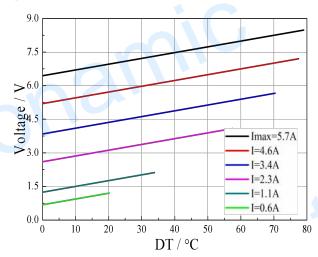


#### Performance Curves at Th=50 °C

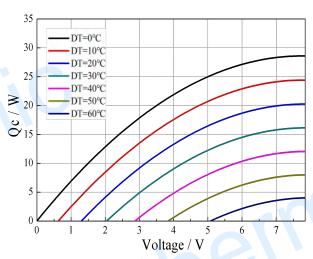


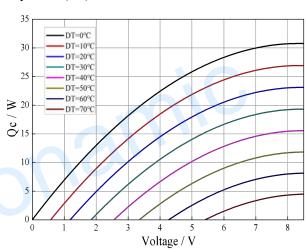
Standard Performance Graph Qc= f(DT)





Standard Performance Graph  $V = f(\Delta T)$ 





Standard Performance Graph Qc = f(V)

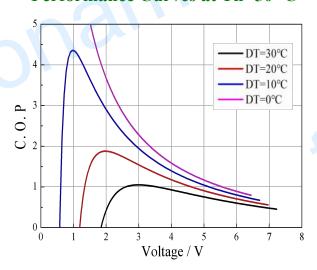
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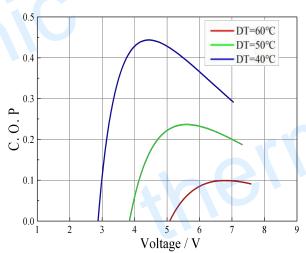
#### Performance Curves at Th=27 °C

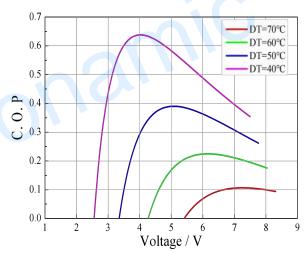
# 5 4 DT=30°C DT=10°C DT=0°C DT=0°C Voltage / V

#### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ( $V \times I$ ).

### **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.